

2SK1807

Silicon N Channel MOS FET

REJ03G0974-0200

(Previous: ADE-208-1321)

Rev.2.00 Sep 07, 2005

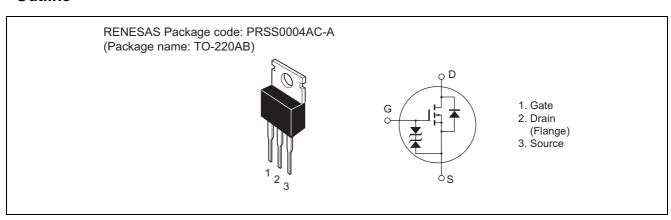
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	900	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	4	А
Drain peak current	I _{D(pulse)} *1	10	А
Body to drain diode reverse drain current	I _{DR}	4	А
Channel dissipation	Pch ^{*2}	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

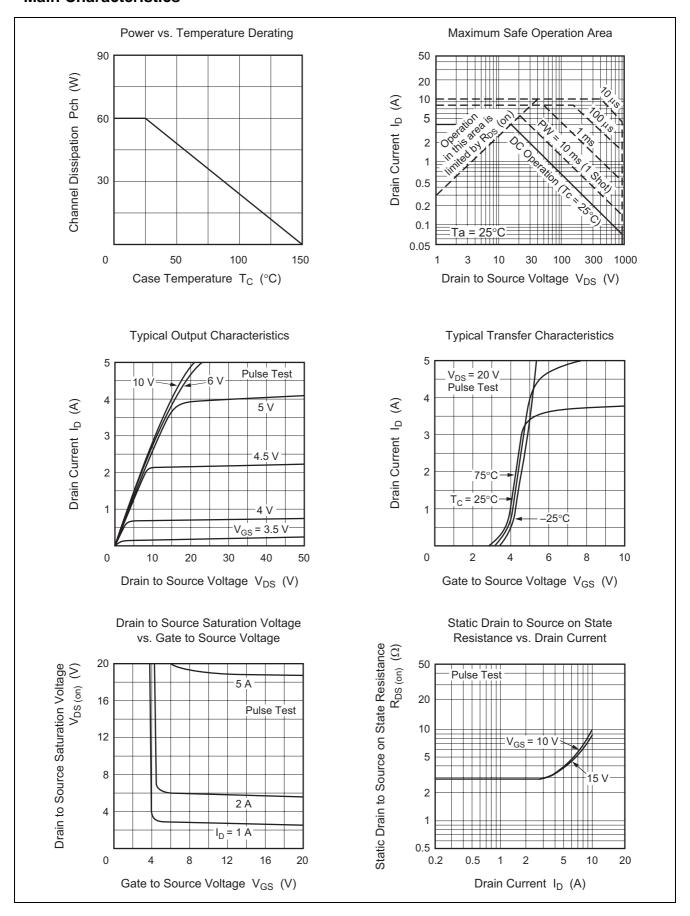
Electrical Characteristics

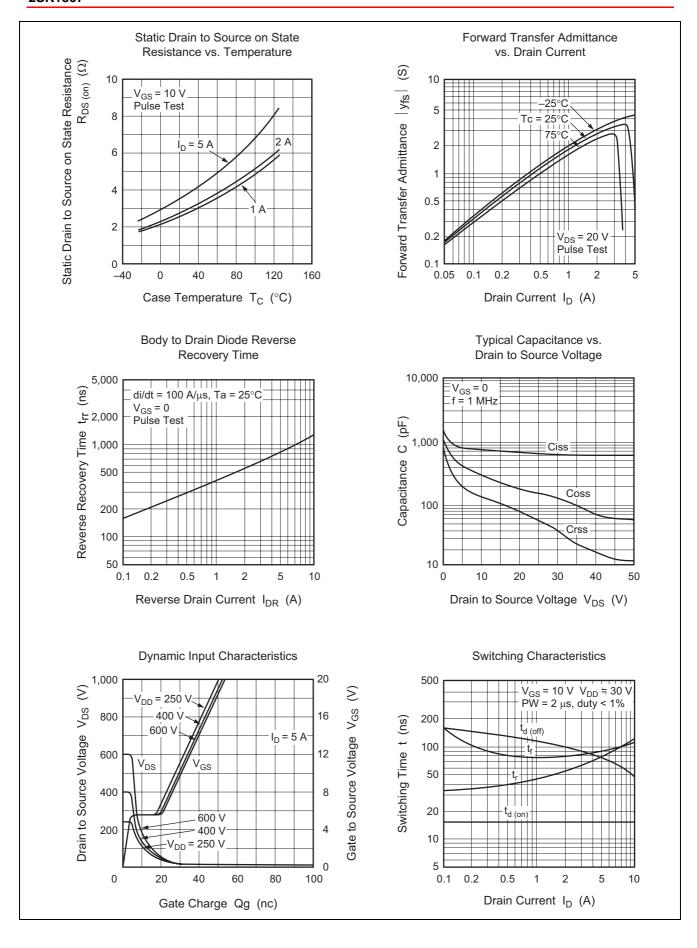
 $(Ta = 25^{\circ}C)$

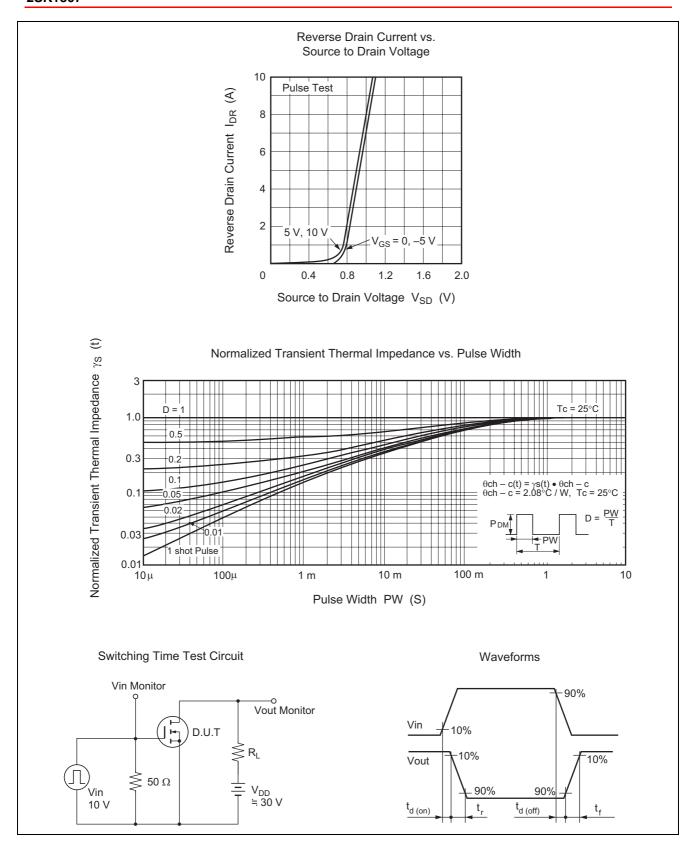
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	900	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±30	_	_	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	V _{DS} = 720 V, V _{GS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R _{DS(on)}	_	3.0	4.0	Ω	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V*}^3$
Forward transfer admittance	y _{fs}	1.7	2.7	_	S	$I_D = 2 \text{ A}, V_{DS} = 20 \text{ V}^{*3}$
Input capacitance	Ciss	_	740	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	305	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	150	_	pF	
Turn-on delay time	t _{d(on)}	_	15	_	ns	$I_D = 2 A$, $V_{GS} = 10 V$,
Rise time	t _r	_	60	_	ns	$R_L = 15 \Omega$
Turn-off delay time	t _{d(off)}	_	100	_	ns	
Fall time	t _f	_	80	_	ns	
Body to drain diode forward voltage	V_{DF}	_	0.9	_	V	$I_F = 4 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	800	_	ns	$I_F = 4 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note: 3. Pulse Test

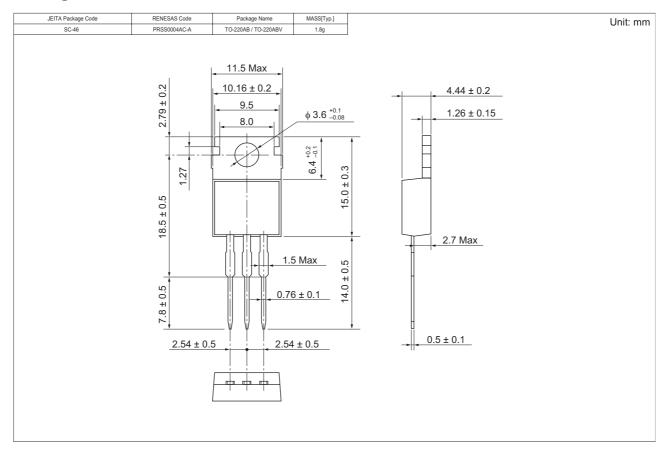
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK1807-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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Renesas Technology Malaysia Sdn. Bhd.

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